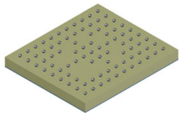
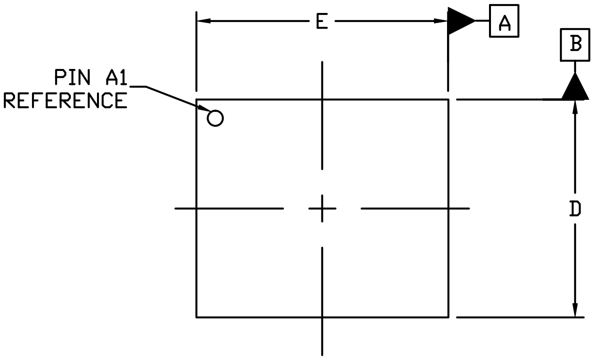
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



WLCSP87 2.643x3.053x0.354
CASE 567ZN
ISSUE C

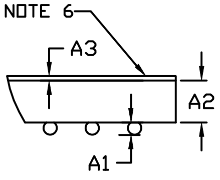
DATE 19 MAY 2023



TOP VIEW

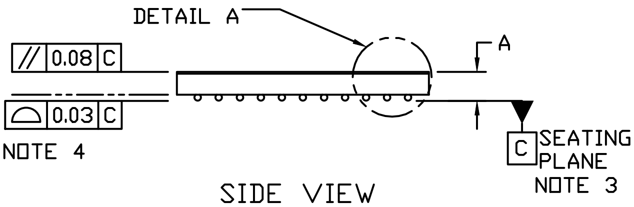
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING.

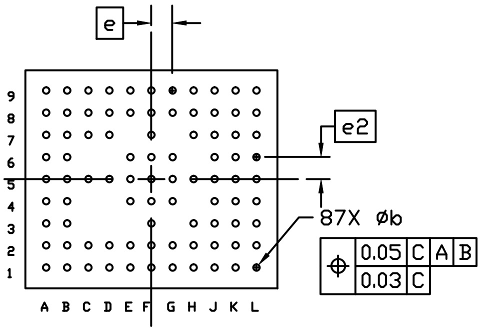


DETAIL A

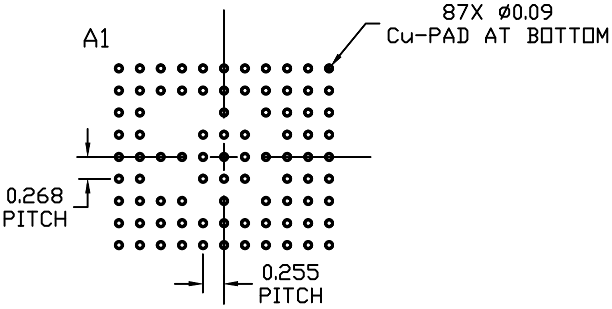
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.329	0.354	0.379
A1	0.060	0.075	0.090
A2	0.241	0.254	0.267
A3	0.025 REF		
b	0.087	0.102	0.117
D	2.593	2.643	2.693
E	3.003	3.053	3.103
e	0.255 BSC		
e2	0.268 BSC		



SIDE VIEW

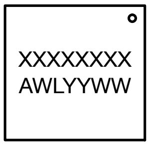


BOTTOM VIEW



RECOMMENDED
MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

GENERIC
MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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